

In re Application of:  
Nguyen, et al.

Group Art Unit: 1756

Examiner: Kathleen Duda

For: Solvent Free Photoresist  
Strip and Residue Removal  
Processing for Post Etching  
of Low-K Films

**MAIL STOP AMENDMENT**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

# CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Michael P. Alexander, on the date shown below.

October 18, 2006

Date \_\_\_\_\_

**Keith M. Tackett**

**RESPONSE TO OFFICE ACTION DATED JULY 18, 2006**

In response to the Office Action dated July 18, 2006, having a shortened statutory period for response set to expire on October 18, 2006, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005735.C1/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**The Claims** are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 7 of this paper.